

1. Features of SM2011Q series:

- AEC-Q200 Grade 1 Compliant .
- 5.70 x 5.40 mm foot Print, 3.00mm Max. height SMD Power Inductor for high frequency application, Operating frequency up to 5MHz.
- Inductance range from 0.47uH to 10.0uH. Custom values are welcomed.
- High saturation current characteristics by distributed gapped metal dust core.
- Ideal for portable device, Pad, E-reader and high density DC to DC Converter.
- Operating Temperature Range: -55°C to 165°C (ambient + self-temperature rise) .
- T & R Qty: 2000 pcs , 13" Reel and Plastic tape: 12mm wide, 8mm pocket spacing.
- RoHS and HF Compliant.

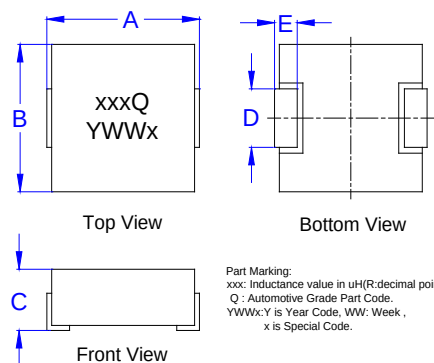


2. Electrical Characteristics of SM2011Q series:

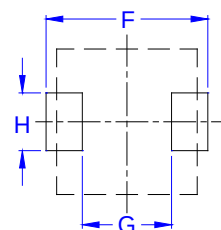
ITG Part Number	OCL (uH) ±20%	DCR (mΩ) Typ. @25°C	DCR (mΩ) Max. @25°C	Saturation Current Isat (A) Typ.	Heat Rating Current Irms (A) Typ.
SM2011Q-R47MHF	0.47	5.25	6.00	13.00	11.00
SM2011Q-R68MHF	0.68	6.75	7.70	13.00	10.00
SM2011Q-R75MHF	0.75	6.80	7.80	11.50	10.00
SM2011Q-1R0MHF	1.00	9.00	10.40	9.50	8.80
SM2011Q-1R5MHF	1.50	14.60	16.80	9.50	8.50
SM2011Q-2R2MHF	2.20	20.40	23.50	7.80	7.50
SM2011Q-3R3MHF	3.30	30.00	34.50	7.50	5.50
SM2011Q-4R7MHF	4.70	40.00	46.00	5.80	4.80
SM2011Q-5R6MHF	5.60	51.00	58.50	4.60	3.50
SM2011Q-6R8MHF	6.80	63.50	73.00	4.00	3.00
SM2011Q-100MHF	10.00	80.00	92.00	2.60	2.50

3. Mechanical Dimensions (unit: mm):

A ± 0.30	B ± 0.20	C ± 0.20	D ± 0.30	E ± 0.20
5.40	5.20	2.80	2.20	1.20



Pad Dimension	SM2011Q
F	6.00 Typ.
G	2.20 Typ.
H	2.50 Typ.

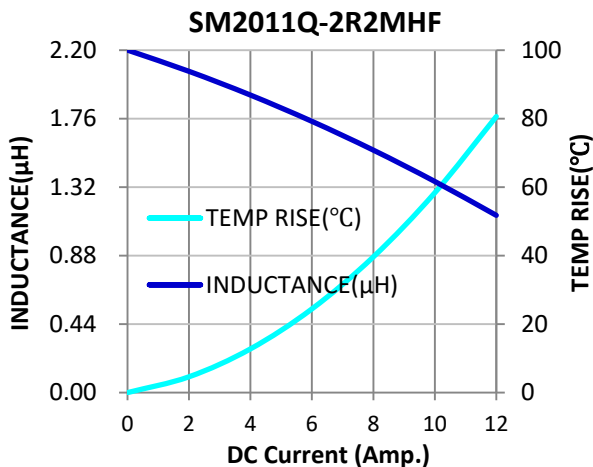
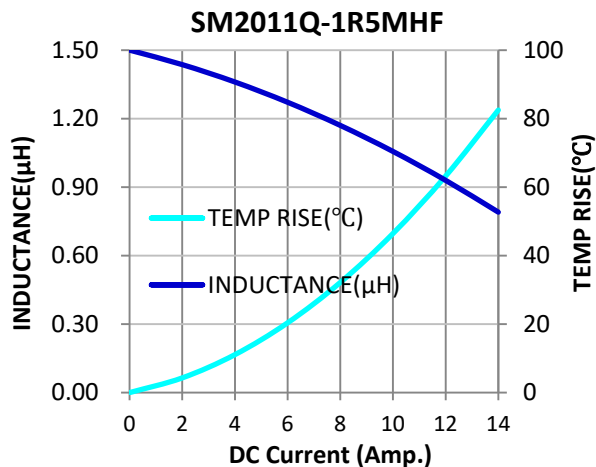
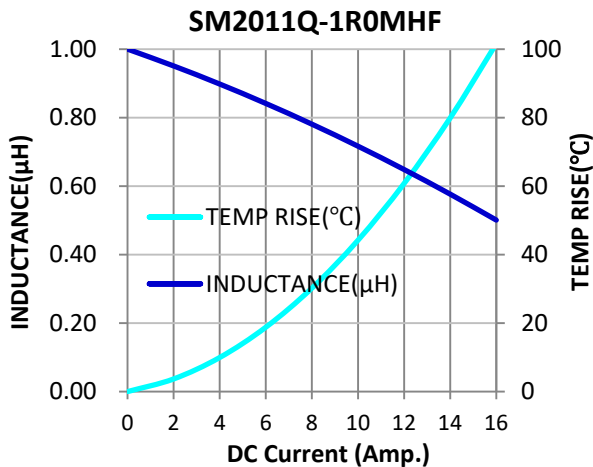
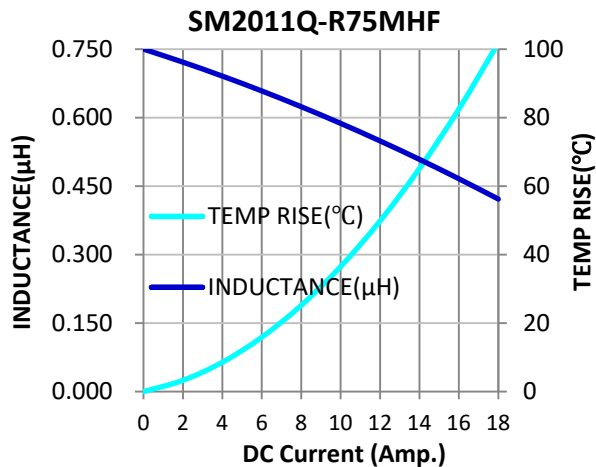
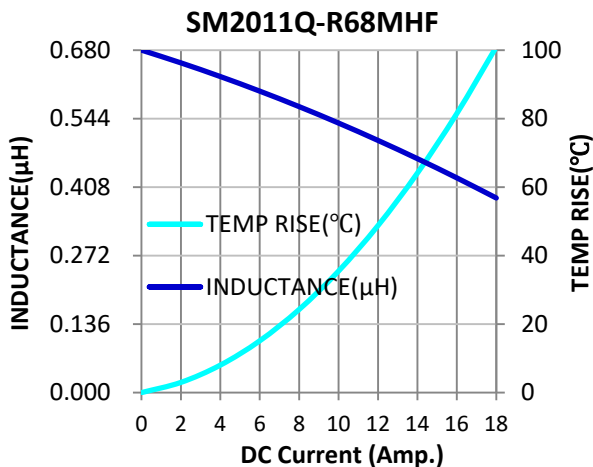
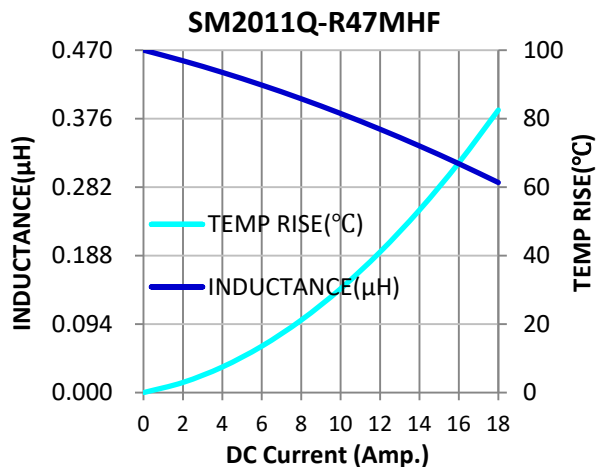


Recommend PCB Layout

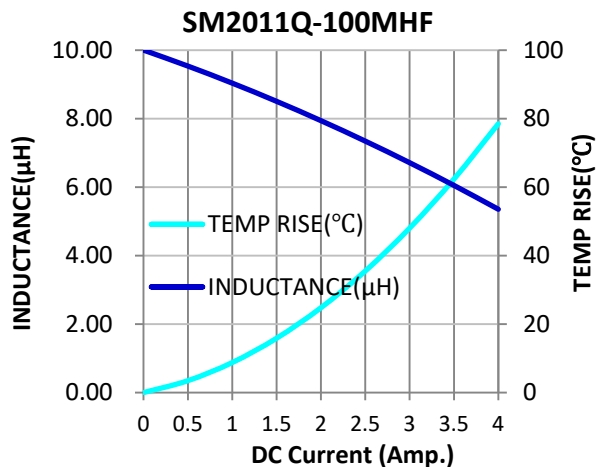
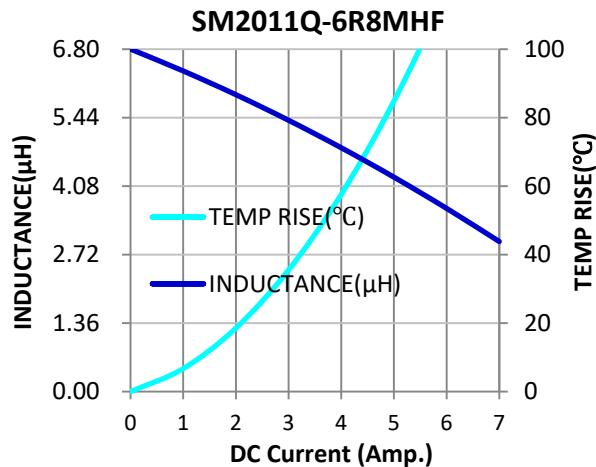
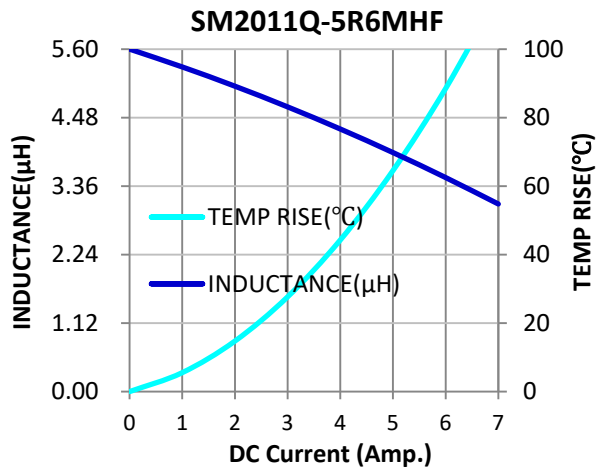
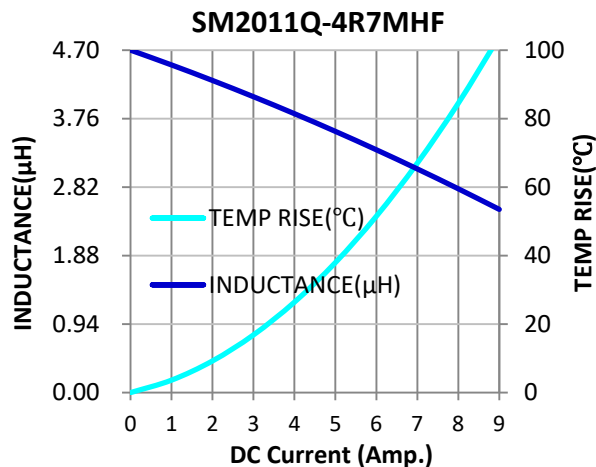
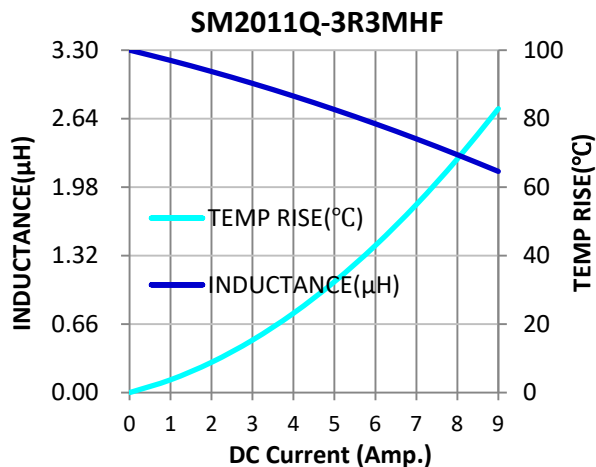
Notes:

1. Test conditions: 100KHz, 1.0V, 25°C ambient temperature .
 2. Isat: DC current that causes inductance to drop 30% (Typ.) from OCL (Ta=25°C).
 3. Irms: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents.
- PCB pad layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed 165° C under worst case operating conditions as verified in the end application.

4. Inductance vs. Temperature Rise Characteristics of SM2011Q Series:

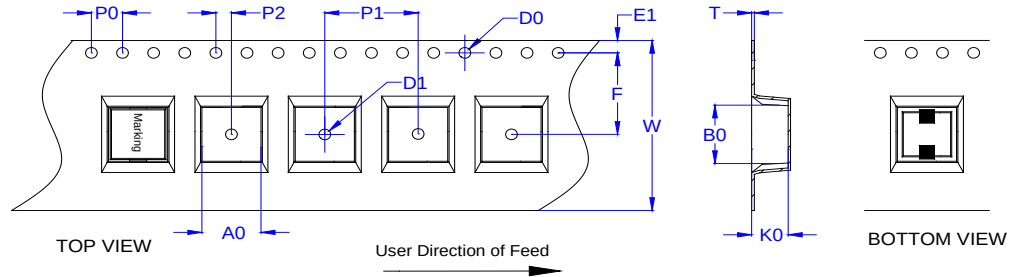


4. Inductance vs. Temperature Rise Characteristics of SM2011Q Series:



5. PACKAGE SPECIFICATION.(UNIT:mm):

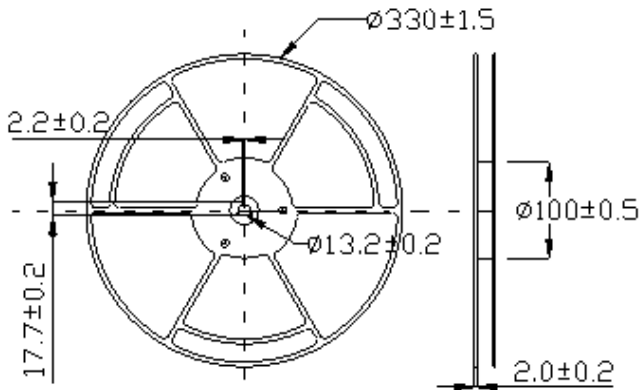
(1).ENCAPSOLATION MODE:



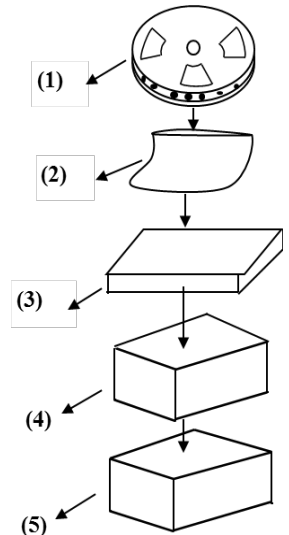
(2).DIMENSION(mm):

W	A0	B0	K0	P1	P0	P2	D0	D1	F	E1	T
12.0±0.30	5.7±0.10	5.9±0.10	3.30±0.15	8.0±0.10	4.0±0.10	2.0±0.10	1.5±0.10	1.5+0.10/-0	5.5±0.10	1.75±0.10	0.35±0.10

(3).REEL SIZE:



(4).PACKAGE MODE:



(5).PACKAGING LIST:

No.	Packing Part	Dimension (mm)	Material	Quantity
1	Reel	330	Plastic	2000Pcs / Reel
2	Bag	450 X 360 X 0.075	Plastic	1Reel / Bag
3	Small Box	340 X 335 X 45	Paper	2Bag / Small Box
4	Middle Box	356 X 350 X 226	Paper	4Small Boxes / Middle Box
5	Outer Box	378 X 362 X 252	Paper	1Middle Box / Outer Box

(6).WEIGHT: N.W: 0.42 g/pcs (APPROX), TOTAL 6.72 Kg(APPROX),G.W:TOTAL 10.22Kg (APPROX).

(7).Storage conditions: -40°C~85°C ,75%RH (Max.).

6.RELIABILITY TEST:

6.1 Mechanical Reliability		
Item	Specification and Requirement	Test Method
Solderability	The surface of terminal immersed shall be minimum of 95% covered with a new coating of solder	Solder heat proof: 1.Precondition: 8 hours steam aging 2.Retention time: 255 ± 5 °C for 5 ± 0.5 seconds
Vibration	Inductance change: Within $\pm 10\%$ Without mechanical damage such as break	1.Vibration frequency:(10 Hz to 2000 Hz) 2.Vibration time:Each four hours (12 times) in X, Y, Z direction: 12 hours in total 3.Amplitude: 1mm or 10 G
Shock	Inductance change: Within $\pm 10\%$ Without mechanical damage such as break	1.Peak value: 100 G 2.Duration of pulse: 6ms 3.Waveform: Half-sine Shocks; 3 times in X, Y, Z direction, 9 times in total
6.2 Endurance Reliability		
Thermal Shock	Inductance change: Within $\pm 10\%$ Without distinct damage in appearance	1.Repeat 1000 cycles as follow: (-55 ± 2 °C; 30 ± 3 min) → ($+165 \pm 2$ °C, 30 ± 3 min) change over time of temperature: $\leq 10s$ 2.Recovery: $24 + 4 / -0$ hours of recovery under the standard condition after the test.
High Temperature & Humidity	Inductance change: Within $\pm 10\%$ Without distinct damage in appearance	85°C85%RH, Duration: $240 + 4 / -0$ hours
Operational Life	Inductance change: Within $\pm 10\%$ Without distinct damage in appearance	1.Rated current (Idc) Environment condition: 85 °C 2.Duration: $1000 + 4 / -0$ hours
Low Temperature Store	Inductance change: Within $\pm 10\%$ Without distinct damage in appearance	Store temperature: -55 ± 2 °C, $1000 + 4 / -0$ hours
High Temperature Store	Inductance change: Within $\pm 10\%$ Without distinct damage in appearance	Store temperature: $+165 \pm 2$ °C, $1000 + 4 / -0$ hours

Soldering Reflow Chart

Solder Reflow Profile:

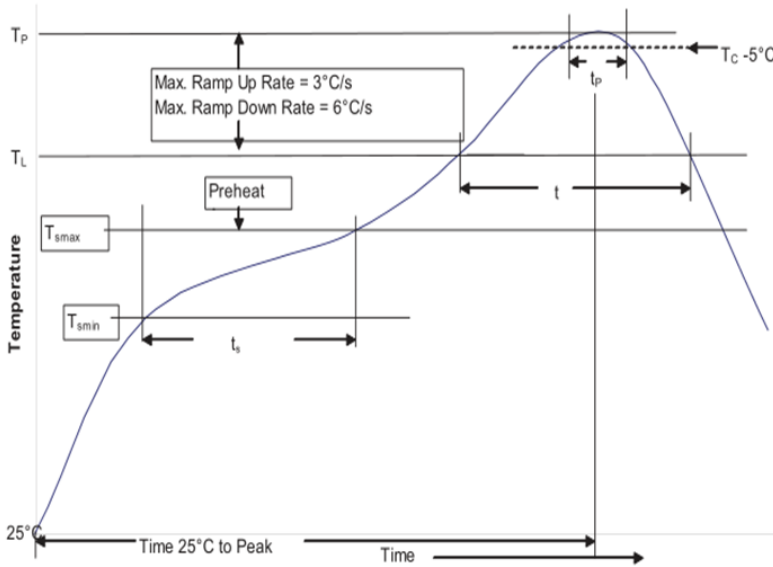


Table 1 - Standard SnPb Solder (T_c)

Package Thickness	Volume mm^3 <350	Volume mm^3 ≥ 350
<2.5mm	235°C	220°C
$\geq 2.5\text{mm}$	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_c)

Package Thickness	Volume mm^3 <350	Volume mm^3 350 - 2000	Volume mm^3 >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JEDEC J-STD-020E:

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100°C	150°C
• Temperature max. (T_{smax})	150°C	200°C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_p)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.